IN THE CLAIMS

1. (Original) A process for forming an article, comprising

heating a reinforced resinous substrate to a thermoforming temperature to form a heated substrate;

contacting a surface of the heated substrate with a surface of shaped surface component, wherein the heated substrate has a sufficient concentration of heated resin at the surface thereof for bonding the heated substrate to the shaped surface component; and

thermoforming the heated substrate at a pressure less than or equal to about 500 psi (3447 kPa) to provide a bond at an interface between the surface of the thermoformed substrate and the surface of the shaped surface component.

- 2. (Original) The process of claim 1, wherein a tie layer is disposed at the interface.
- 3. (Original) The process of claim 1, wherein the shaped surface component comprises a film layer, and further wherein the interface is between the surface of the thermoformed substrate and a surface of the film layer.
- 4. (Original) The process of claim 3, wherein a tie layer is disposed at the interface.
- 5. (Original) The process of claim 1, wherein the shaped surface component comprises a film layer and a first compatible layer, and further wherein the interface is between the surface of the thermoformed substrate and a surface of the first compatible layer opposite the film layer.
- 6. (Original) The process of claim 5, wherein a tie layer is disposed at the interface.

- 7. (Original) The process of claim 1, comprising forming the shaped surface component by thermoforming in a mold.
- 8. (Original) The process of claim 7, wherein the thermoformed surface component is cooled in the mold, then contacted with the heated substrate without removal from the mold.
- 9. (Original) The process of claim 7, further comprising removing the thermoformed surface component from the mold, and placing the thermoformed surface component in or on a second mold prior to contacting with the heated substrate.
- 10. (Original) The process of claim 1, wherein a surface of the shaped surface component opposite the heated substrate is adjacent a mold form for maintaining the shaped surface component at a temperature below the thermoforming temperature.
- 11. (Original) The process of claim 1, wherein thermoforming is at a pressure about 1 (6.9 kPa) to about 500 psi (3447 kPa).
- 12. (Original) The process of claim 1, wherein thermoforming is at a pressure of about 10 (69 kPa) to about 100 psi (690 kPa).
- 13. (Original) The process of claim 1, wherein a surface of the heated substrate opposite the shaped surface component is in contact with a conformable pressure-transmitting medium, and further comprising thermoforming the heated substrate by transmitting a thermoforming pressure through the medium.
- 14. (Original) The process of claim 1, wherein a surface of the heated substrate opposite the shaped surface component is in contact with a mold form, and further comprising thermoforming the heated substrate by transmitting a thermoforming pressure through the mold form.

- 15. (Currently Amended) The process of-claim 1 claim 3, further comprising a balancing layer positioned adjacent the heated substrate on a side opposite the film layer.
- 16. (Original) The process of claim 1, wherein the surface component or substrate comprises a polycarbonate, acrylonitrile-styrene-acrylic, acrylic, acrylonitrile-butadiene-styrene, polybutylene terephthalate, polyethylene terephthalate, polyolefin, arylate polyester, or a blend, alloy, or copolymer comprising at least one of the foregoing resins.
- 17. (Original) The process of claim 1, wherein the surface component comprises a polymer comprising units of an arylate polyester.
- 18. (Original) The process of claim 1, wherein the surface component comprises a film layer comprising arylate polyester units and a first compatible layer comprising an additive for providing an aesthetic effect.
- 19. (Original) The process of claim 18, wherein the film layer comprises a block copolyester carbonate comprising arylate polyester-containing block segments in combination with organic carbonate block segments and the first compatible layer comprises a colorant.
 - 20. (Original) A process for forming an article, comprising

thermoforming a reinforced resinous substrate to provide a shaped reinforced resinous substrate;

thermoforming a surface component, wherein the shape of the surface component substantially matches the shape of the reinforced resinous substrate; and

joining a surface of the shaped reinforced resinous substrate with a surface of the surface component at an interface.

- 21. (Original) The process of claim 20, wherein the joining is by thermoforming or use of an adhesive.
 - 22. (Withdrawn) An article made by the process of claim 1.
 - 23. (Withdrawn) An article made by the process of claim 20.
 - 24 27. (Cancelled)
- 28. (Previously Presented) The process of claim 16, wherein the surface component or substrate comprises acrylonitrile-styrene-acrylic, acrylic, acrylic, acrylonitrile-butadiene-styrene, polybutylene terephthalate, polyethylene terephthalate, polyethylen
- 29. (Previously Presented) The process of claim 28, wherein the surface component or substrate comprises acrylonitrile-styrene-acrylic, acrylic, acrylonitrile-butadiene-styrene, polybutylene terephthalate, polyethylene terephthalate, arylate polyester, or a blend, alloy, or copolymer comprising at least one of the foregoing resins.
- 30. (Previously Presented) The process of claim 29, wherein the surface component or substrate comprises acrylonitrile-styrene-acrylic, acrylonitrile-butadiene-styrene, polybutylene terephthalate, polyethylene terephthalate, or a blend, alloy, or copolymer comprising at least one of the foregoing resins.
- 31. (New) The process of claim 15, wherein the balancing layer has a coefficient of thermal expansion that matches the film layer.